

规格书编号

SPEC NO :

产品规格书

SPECIFICATION

CUSTOMER 客 户 : _____

PRODUCT 产 品 : _____ SAW FILTER

MODEL NO 型 号 : _____ HDF422A F11

PREPARED 编 制 : _____ CHECKED 审 核 : _____

APPROVED 批 准 : _____ D A T E 日 期 : _____ 2011-3-8

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

更改历史记录

History Record

[illegible]

1. SCOPE

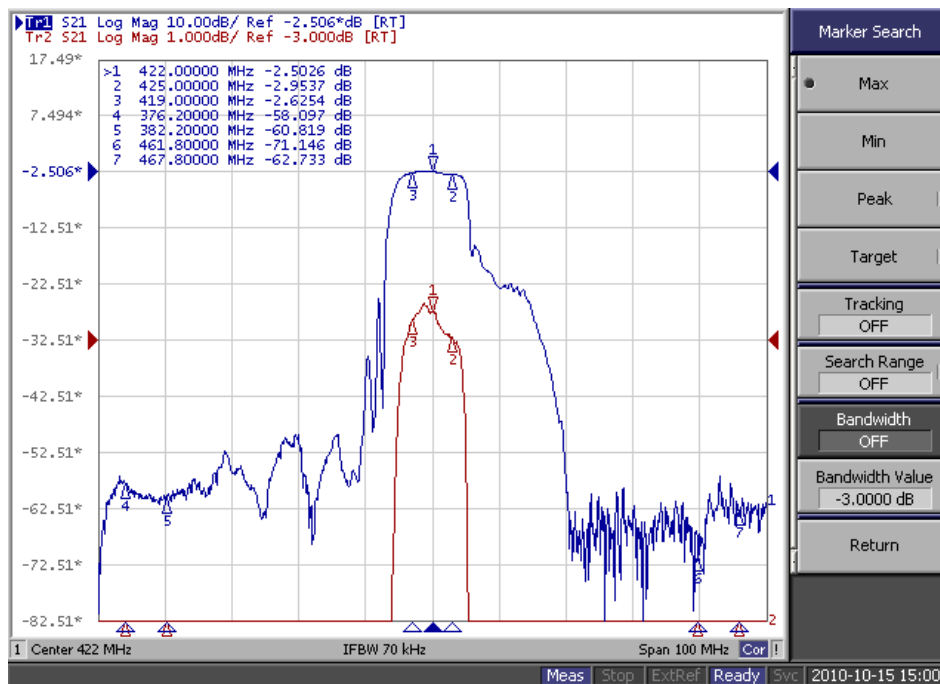
This specification shall cover the characteristics of SAW filter With F422A used for the page system.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-40°C to +85°C
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

2-1. Typical frequency response

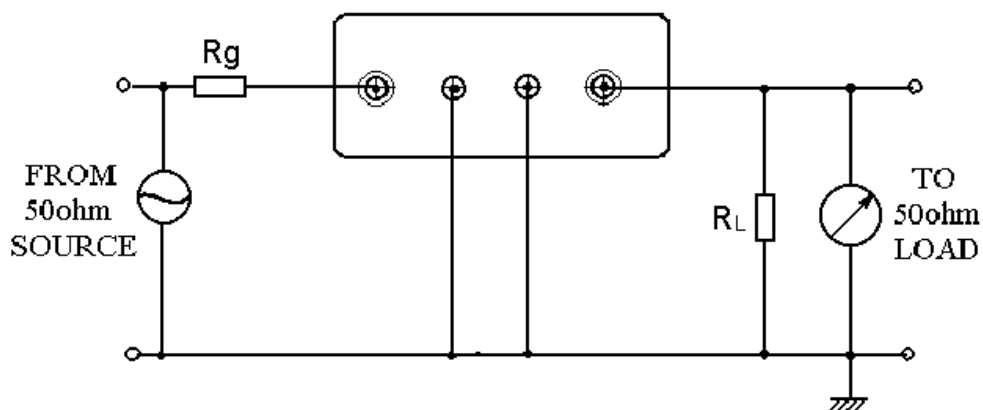


2-2. Electrical characteristics

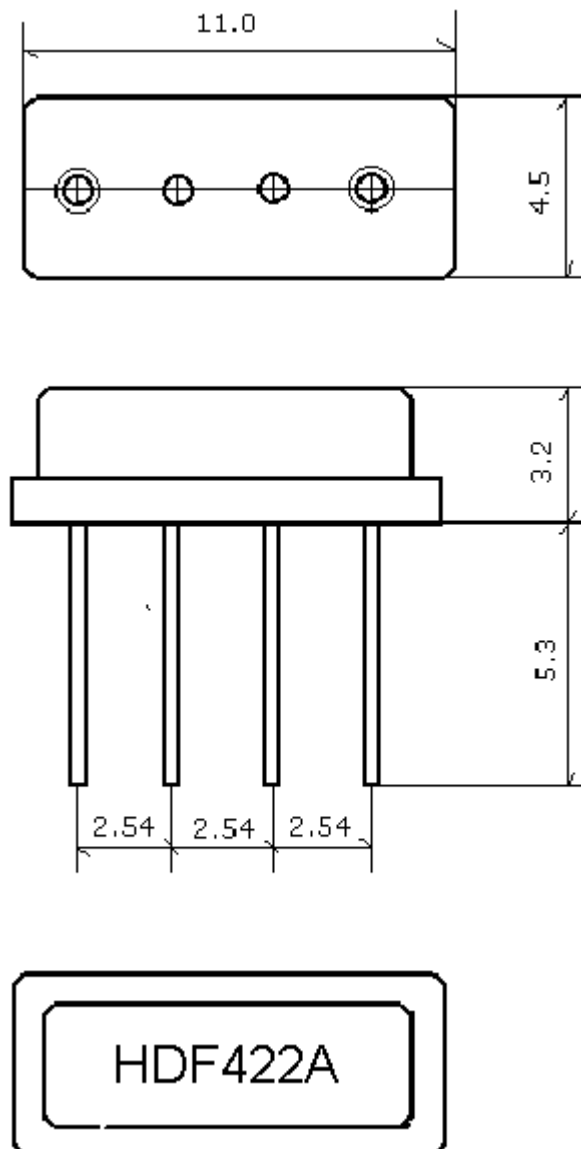
Part number	F422A	Unit
Nominal center frequency (Fo)	422	MHz
Insertion Loss		
1.fo-45.8~fo-39.8 MHz	50min.	dB
2.fo±3.0 MHz	4.0max.	
3.fo +39.8~ fo +45.8MHz	45min.	

Ripple (with Fo $\pm 3.0\text{MHz}$)	2.0max	dB
Input/Output Impedance(Nominal)	50//0	Ω/pF

3 . TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-2 Low temperature exposure

Subject the device to -40°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in 2-2.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of +85°C for 30 Minutes. Then release the device into the room conditions

for 24 hours prior to the measurement. It shall meet the specifications in 2-2.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C}\pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in 2-2.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C}\pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in 2-2.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in 2-2.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in 2-2.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.